



# Ultrananocrystalline Diamond: Tuning Materials Properties via Plasma Chemistry

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## ABSTRACT

Ultra-nanocrystalline diamond (UNCD) films are synthesized by a microwave plasma enhanced chemical vapor deposition (MPCVD) method using a  $\text{CH}_4$  (1%)/Ar (99%) gas mixture. Tuning the electrical and structural characteristics of the films is performed via substituting a percentage of the Ar with 1-20% N or H. Electron microscopies indicate a change in grain size and shape, and x-ray spectroscopies indicate local changes in bonding structure. Most strikingly, the electrical conductivity of the nitrogen-doped UNCD films increases by five orders of magnitude (up to  $143 \text{ W}^{-1}\text{cm}^{-1}$ ) with increasing nitrogen content. Conductivity and Hall measurements indicate that these films have the highest n-type conductivity and carrier concentration demonstrated for phase-pure diamond thin films. Grain boundary conduction is proposed to explain the remarkable transport properties of these films.

## Ultrananocrystalline Diamond (UNCD)

**Synthesis:**  
Microwave Plasma Chemical Vapor Deposition

### Deposition Parameters:

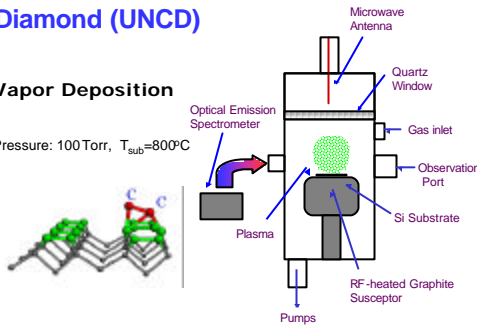
Plasma Composition: Ar/ $\text{CH}_4$  99%/1% Total Pressure: 100 Torr,  $T_{\text{sub}}=800^\circ\text{C}$

### Growth Mechanism:

$\text{C}_2$  dimer insertion

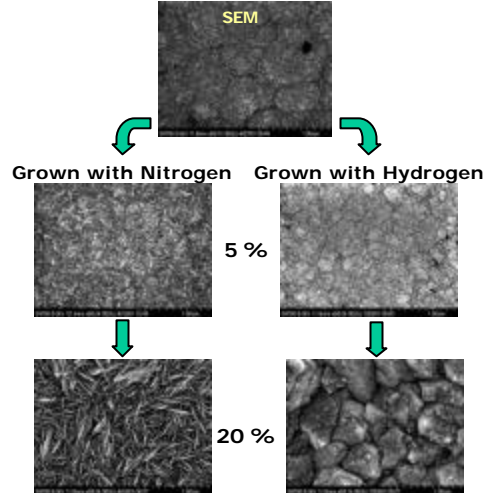
### Structural Properties:

- 2-5 nm grain sizes; atomically-abrupt grain boundaries; conformal coating
- Phase-pure (<3%  $\text{sp}^2$ -bonded carbon)



## Control of Structural Properties in UNCD

### Surface Morphology of Plain UNCD

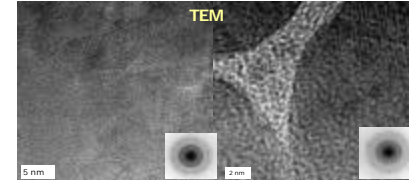


- The bulk structure & surface morphology can be controlled by altering the growth plasma chemistry

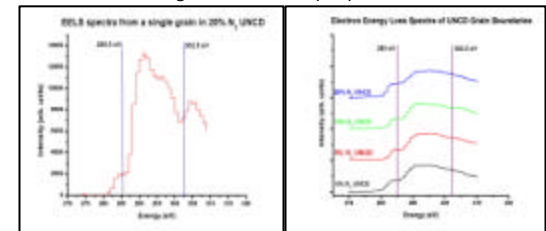
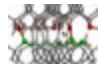
### Nitrogen Growth: UNCD Structure

Ar:99 /  $\text{CH}_4$ :1

Ar:79 /  $\text{CH}_4$ :1 /  $\text{N}_2$ :20



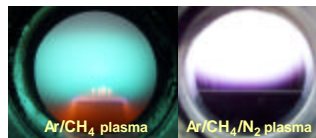
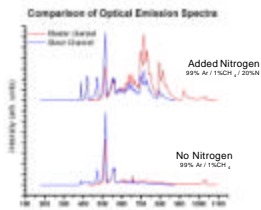
- Nitrogen doping of UNCD alters the nanostructure of the film, in turn affecting its materials properties.



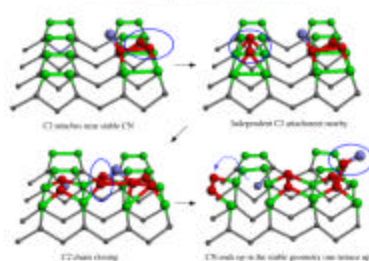
- UNCD grains = phase pure diamond
- UNCD grain boundaries = disordered C

## Control of Plasma Growth Species with Nitrogen

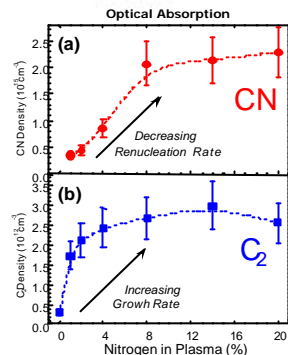
- Addition of N (1 -20%) increases  $\text{C}_2$  dimer and CN specie concentrations



### Diamond (100) growth with $\text{C}_2$ and CN

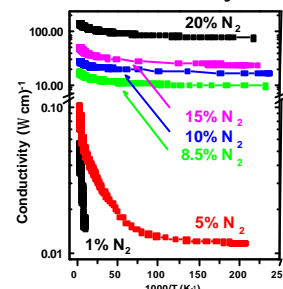


- CN and  $\text{C}_2$  co-adsorption leads to CN-mediated  $\text{C}_2$  chain growth.
- CN addition does not lead to nucleation;  $\text{C}_2$  addition results in both growth and nucleation



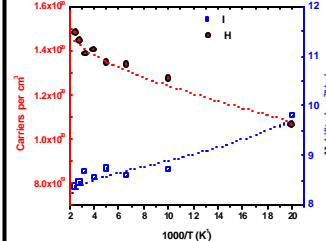
## Control of Electronic Properties

### Conductivity



- N doping: UNCD becomes semi-metallic with grain boundary conductivity
- H doping: UNCD becomes insulating
- The conductivity is a strong fcn. of % N in plasma.
- Results similar to heavily boron-doped diamond

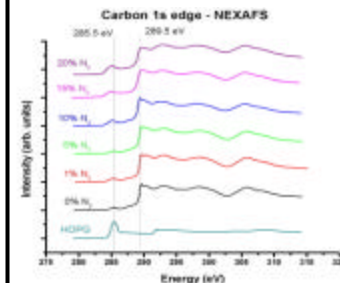
### Hall Effect



- UNCD is an n-type semiconductor
- %N in plasma tunes carrier concentration and mobility.

Acknowledgement: Lake Shore Cryotronics for Hall Measurements.

## Control of Structural Composition



- Moderate increase of  $\text{sp}^2/\text{sp}^3$  bonded C ratio
- TEM indicates pure diamond structure in grains
- May indicate grain boundary character is changing

Acknowledgement: Advanced Light Source, Lawrence Berkeley National Laboratory

## Summary/Future work

In summary, control over structural and electronic UNCD properties has been demonstrated via N and H doping. Doping with N has in particular proven to be useful for producing highly-conductive, n-type UNCD. We propose that grain boundary conduction involving carbon p-states is responsible for the high electrical conductivities in these films.

Near-future work will include increasing the electronic capabilities of UNCD via doping with B and P and fabricating initial electronic devices, simultaneously controlling the film structure with N or H.